



ESP32-C3-MINI-1

User Manual



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Catalog

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I Functional Overview

1.1 Introduction

ESP32-C3-MINI-1 is a WIFI module based on the ESP32-C3 chip solution.

ESP32-C3-MINI-1 is a general-purpose Wi-Fi module, small in size, rich in peripheral interfaces, equipped with 4 MB embedded flash, and equipped with a RISC-V 32-bit single-core processor. The chip integrates a wealth of peripherals, including UART, I2C, I2S, infrared remote control module (remote control peripheral), LED PWM controller, general DMA controller, TWAI® controller, USB serial port/JTAG controller, temperature sensor and analog /Digital converter, also has a single-wire, two-wire, four-wire SPI interface.

It can be used in smart home, industrial automation, healthcare, consumer electronics and other fields.



1.2 Features

- 4 MB embedded flash;
- Support AT commands;
- Support serial communication and flow control. The baud rate is up to 128000.
- Support automatic and manual networking.

II Electrical Characteristics

2.1 Absolute maximum ratings

Symbol	Parameter	Minimum	Maximum	Unit
VDD33	Power pin voltage	- 0.3	3.6	V
TSTORE	Storage temperature	- 40	85	° C

Chart 2- 1 Absolute maximum ratings

2.2 Recommended working conditions

Symbol	Parameter	Minimum	Typical	Maximum	Unit
VDD33	Power Pin Voltage	3.0	3.3	3.6	V
IVDD	Supply current of external power supply	0.5	—	—	A

T	Recommended working temperature	- 40	—	85	° C
Humidity	Humidity	—	85	—	%RH
I _{max}	Peak current			400	mA
I	Average current			100	mA

Chart 2- 2 Recommended working conditions

2.3 RF Characteristics

Working channel center frequency range		2412~2484MHz
Wi-Fi		Protocol IEEE802.11b/g/n
Antenna type		PCB
Distance	With router @Mercury MW305R	200m
	Between Modules	200m

Chart 2- 3 RF Characteristics

III Hardware Description

3.1 Mechanical size and pin definition

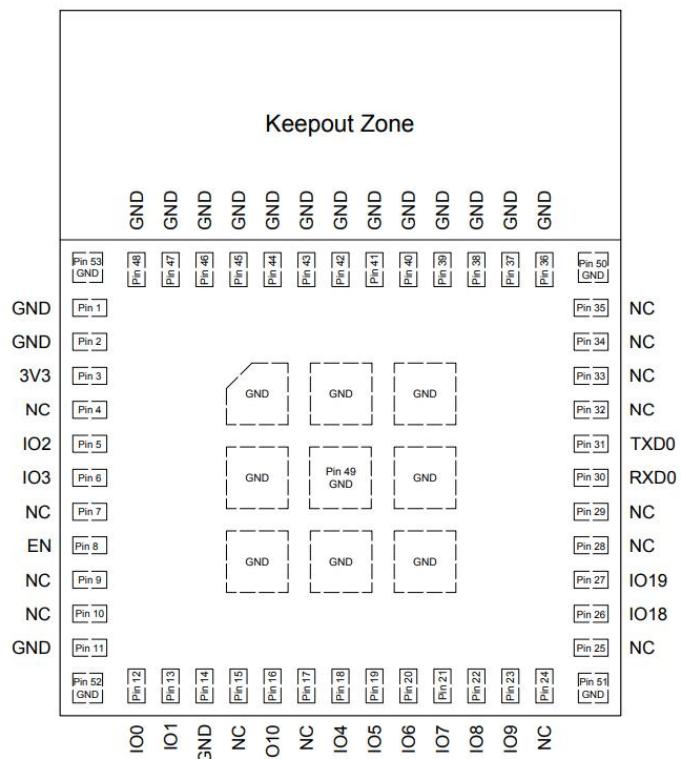


Chart 3- 1 Pin layout diagram

Name	Serial number	Type	Function
GND	1, 2, 11, 14, 36-53	P	Grounded
3V3	3	P	Powered by
NC	4, 7, 9, 10, 15, 17, 24, 25, 28, 29, 32-35	—	Empty pin
IO2	5	I/O/T	GPIO2, ADC1_CH2, FSPIQ
IO3	6	I/O/T	GPIO3, ADC1_CH3
EN	8	I	High level: chip enable; low level: chip off; Be careful not to let the EN pin float.
IO0	12	I/O/T	GPIO0, ADC1_CH0, XTAL_32K_P
IO1	13	I/O/T	GPIO1, ADC1_CH1, XTAL_32K_N
IO10	16	I/O/T	GPIO10, FSPICS0
IO4	18	I/O/T	GPIO4, ADC1_CH4, FSPIHD, MTMS
IO5	19	I/O/T	GPIO5, ADC2_CH0, FSPIWP, MTDI
IO6	20	I/O/T	GPIO6, FSPICLK, MTCK
IO7	21	I/O/T	GPIO7, FSPID, MTDO
IO8	22	I/O/T	GPIO8
IO9	23	I/O/T	GPIO9
IO18	26	I/O/T	GPIO18, USB_D-
IO19	27	I/O/T	GPIO19, USB_D+
RXD0	30	I/O/T	GPIO20, U0RXD
TXD0	31	I/O/T	GPIO21, U0TXD

1 P: power supply; I: input; O: output; T: can be set to high impedance.

Chart 3- 2 Pin definition list

3.2 Minimal Schematic

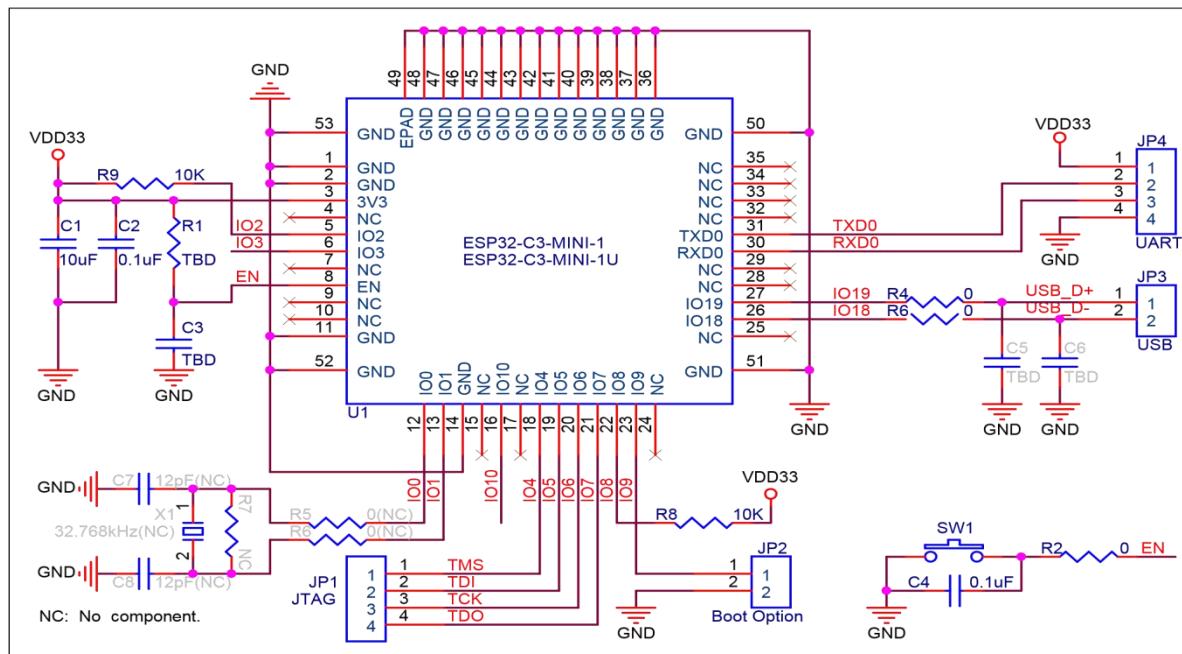


Chart 3- 3 Minimal Schematic

3.3 Module size

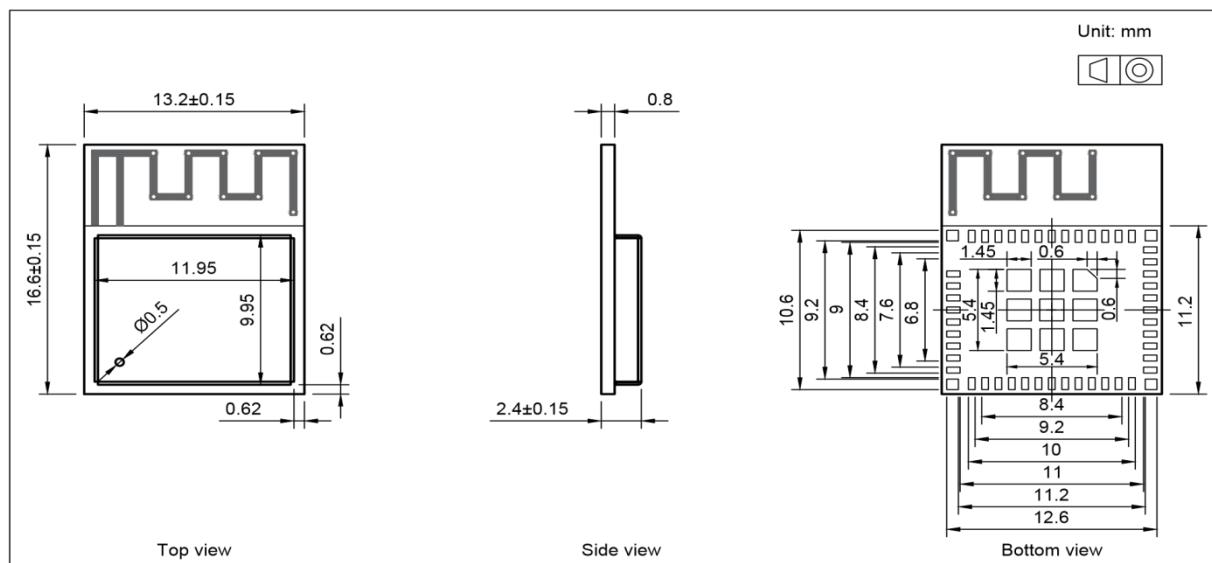


Chart 3- 4 Module size

3.4 PCB package pattern

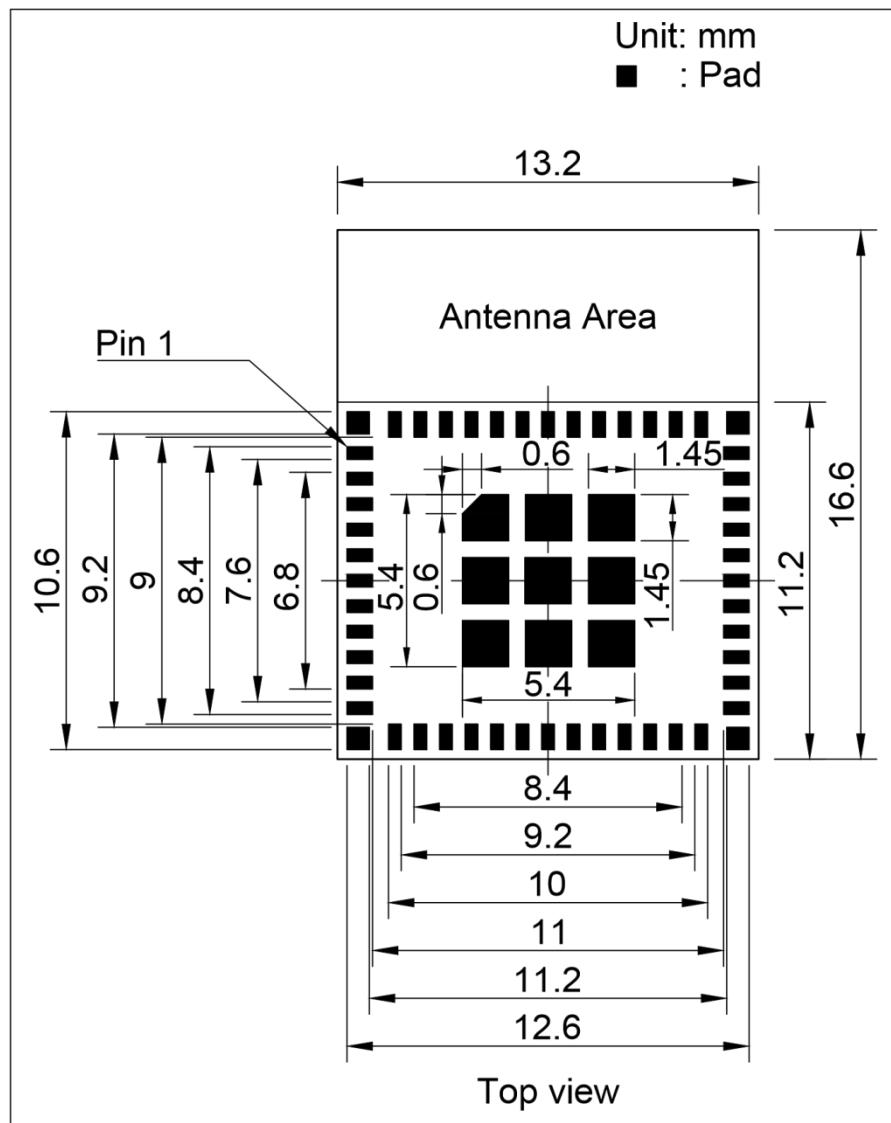


Chart 3- 5 PCB package

IV AT Command

For AT commands, please refer to the download page <ESP32-C3-MINI-1_AT_Bin_V2.2.0.0>

V Common Questions

5.1 Unsatisfactory transmission distance

- When there is a straight line communication obstacle, the communication distance will be attenuated accordingly;
- Temperature, humidity, and co-frequency interference will increase the communication packet loss rate;
- The ground absorbs and reflects radio waves, and the test effect is poor when it is close to the ground;
- Sea water has a strong ability to absorb radio waves, so the seaside test effect is poor;
- If there is a metal object near the antenna or placed in a metal shell, the signal attenuation will be very serious;
- The power register is set incorrectly, and the air speed is set too high (the higher the air speed, the closer the distance);
- The low voltage of the power supply at room temperature is lower than the recommended value, the lower the voltage, the lower the power output.

5.2 Module is easily damaged

- Please check the power supply to ensure that it is within the recommended power supply voltage. If it exceeds the maximum value, it will cause permanent damage to the module;
- Please check the stability of the power supply, and the voltage should not fluctuate greatly and frequently;
- Please ensure that the installation and use process is anti-static, and high-frequency components are electrostatically sensitive;
- Please ensure that the humidity should not be too high during installation and use, and some components are humidity sensitive devices;
- If there is no special requirement, it is not recommended to use it at too high or too low temperature.

5.3 Bit error rate is too high

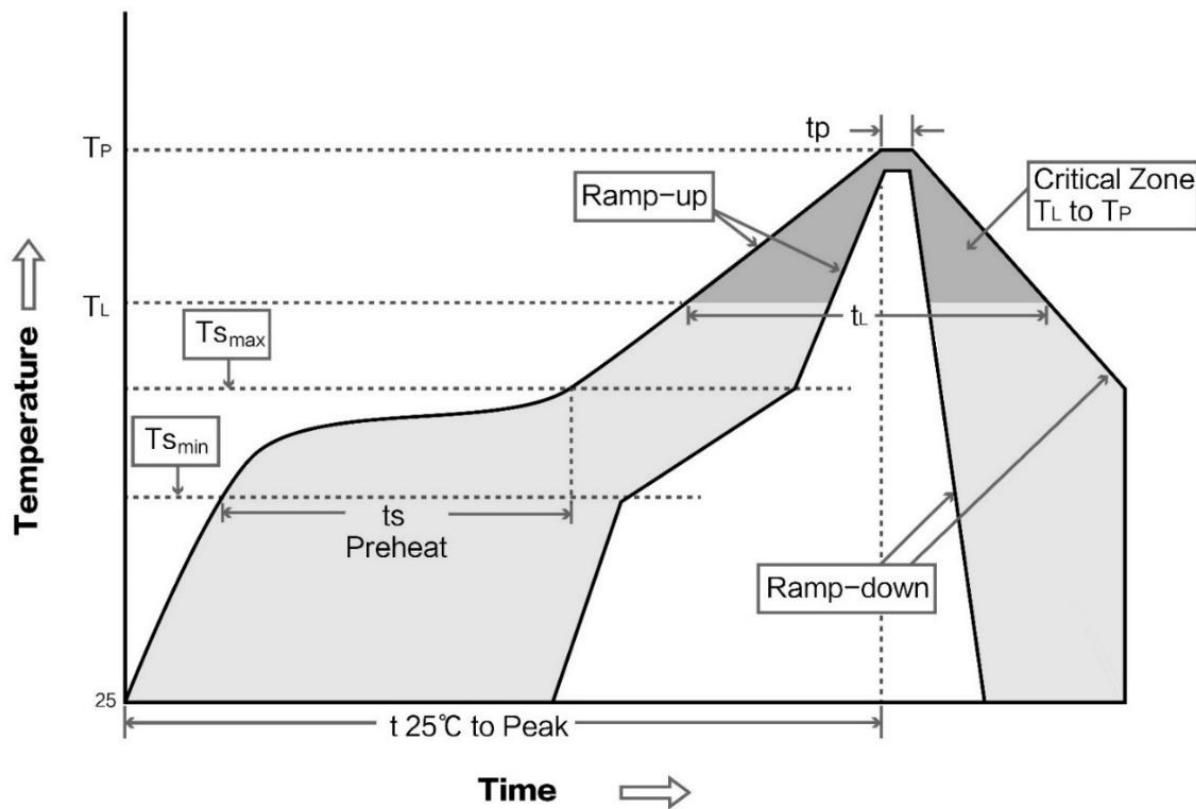
- There is co-frequency signal interference nearby, stay away from the interference source or modify the frequency and channel to avoid interference;
- The clock waveform on the UART is not standard, check whether there is interference on the UART line;
- Unsatisfactory power supply may also cause garbled codes, so the reliability of the power supply must be ensured;

VI Welding Operation Guidance

6.1 Reflow temperature

Profile Feature	Curve characteristics	Sn-Pb Assembly	Pb-Free Assembly
Solder Paste	Tin paste	Sn63/Pb37	Sn96.5/Ag3/Cu0.5
Preheat Temperature min (Tsmin)	Minimum preheating temperature	100°C	150°C
Preheat temperature max (Tsmax)	Maximum preheating temperature	150°C	200°C
Preheat Time (Tsmin to Tsmax) (ts)	Preheat time	60–120 sec	60–120 sec
Average ramp-up rate(Tsmax to Tp)	Average ascent rate	3°C/second max	3°C/second max
Liquidous Temperature (TL)	Liquidus temperature	183°C	217°C
Time (tL) Maintained Above (TL)	Time above liquidus	60–90 sec	30–90 sec
Peak temperature (Tp)	Peak temperature	220–235°C	230–250°C
Aveage ramp-down rate (Tp to Tsmax)	Average rate of descent	6°C/second max	6°C/second max
Time 25°C to peak temperature	Time from 25°C to peak temperature	6 minutes max	8 minutes max

6.2 Reflow soldering curve



VII Disclaimer

- This manual shall try its best to provide a comprehensive and detailed introduction based on the existing information. The company reserves the right to modify the content of the manual without further notice.
- This manual is only used as a guide, all the information in the manual does not constitute any express or implied guarantee.

Revise History

Version	Revision Date	Revision Description	Maintainer
1.0	2021-03-18	Initial version	-

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